

[B] [EAST - Untitled:1]										
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<input type="checkbox"/> Drafts <input type="checkbox"/> Pending <input type="checkbox"/> Active <input checked="" type="checkbox"/> L1: (520) (205/123).CCIS. <input checked="" type="checkbox"/> L2: (210310) high adj density <input checked="" type="checkbox"/> L3: (96949) low adj density <input checked="" type="checkbox"/> L4: (31460) 12 same 13 <input checked="" type="checkbox"/> L5: (6) 14 and 11  <input checked="" type="checkbox"/> Failed <input checked="" type="checkbox"/> Saved <input checked="" type="checkbox"/> Favorites <input checked="" type="checkbox"/> Tagged (0) <input checked="" type="checkbox"/> UDC <input checked="" type="checkbox"/> Queue <input checked="" type="checkbox"/> Trash										
<input type="checkbox"/> Search <input type="checkbox"/> List <input type="checkbox"/> Browse <input type="checkbox"/> Guess <input type="checkbox"/> Date										
<b>DB:</b> USPSPUB-USPAI <input type="checkbox"/> Books Default Operator: AND <input checked="" type="checkbox"/>										
14 and 11										

[A] BRS form    ISBN form    Images    Text    HTML

Document ID	Issue Date	Pages	Title	Current OR	Current XRef	Inventor	U	S	C	P	I	31	PT
1 US 20030221967 A1	20031204	8	Via filling method	205/103	205/105; 205/123; al.	Tsuchida, Hideki et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>					
2 US 6035294 B2	20041228		Electrolytic copper plating method	205/98	205/101; 205/102; al.	Tsuchida, Hideki et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>					
3 US 6761814 B2	20040713		Via filling method	205/118	205/103; 205/123;	Kusaka, Masaru et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>					
4 US 6440289 B1	20020827		Method for improving seed layer	205/103	205/102; Woo, Christy Mei-Chu	Woo, Christy Mei-Chu	<input checked="" type="checkbox"/>	<input type="checkbox"/>					
5 US 6107186 A	20000822		Electroplating for semiconductor	438/633	205/104; Et al.	Erb, Darrell M.	<input checked="" type="checkbox"/>	<input type="checkbox"/>					
6 US 5503731 A	19960402		High planarity high density in-laid metalization patterns by damascene-CMP	205/98	205/104; 205/123; Konuma, Toshimitsu et al.	Konuma, Toshimitsu et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>					
			Method for producing electrodes of semiconductor device	205/124;			<input checked="" type="checkbox"/>	<input type="checkbox"/>					

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Pre-Entry		